

# SOT2007-1

LPGA388, low profile ball grid array package, 388 terminals,  
0.56 mm minimum pitch, 15 mm x 15 mm x 1.55 mm body,  
bare die

3 August 2020

Package information

## 1 Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	LPGA388
<b>Package style descriptive code</b>	LPGA (low profile ball grid array)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	07-07-2020
<b>Manufacturer package code</b>	98ASA01377D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	14.85	15	15.15	mm
package width	14.85	15	15.15	mm
package height	1.4	1.55	1.7	mm
nominal pitch	-	0.56	-	mm
actual quantity of termination	-	388	-	



LPGA388, low profile ball grid array package, 388 terminals, 0.56 mm minimum pitch, 15 mm x 15 mm x 1.55 mm body, bare die

2 Package outline

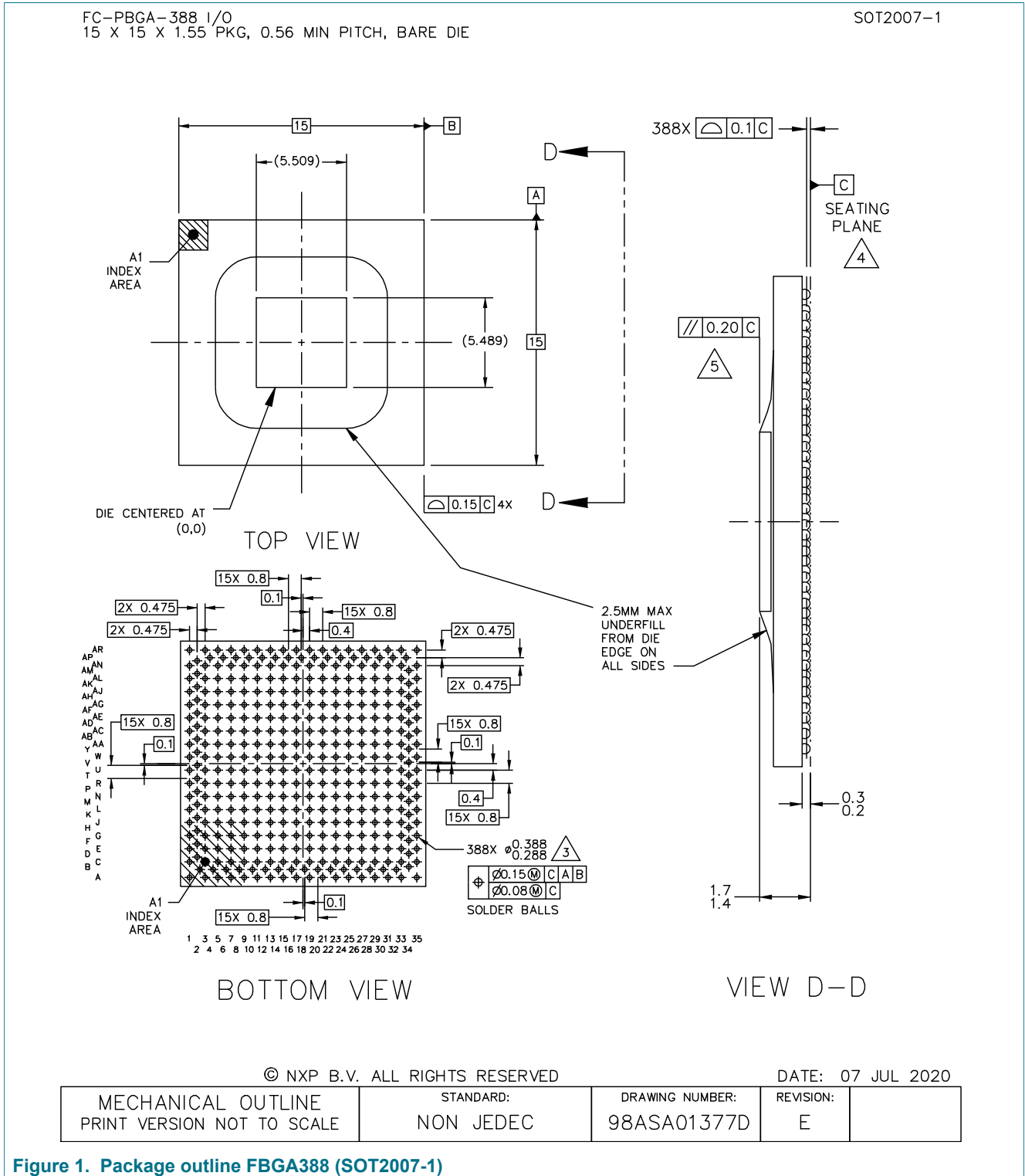


Figure 1. Package outline FBGA388 (SOT2007-1)

LPGA388, low profile ball grid array package, 388 terminals, 0.56 mm minimum pitch, 15 mm x 15 mm x 1.55 mm body, bare die

3 Soldering

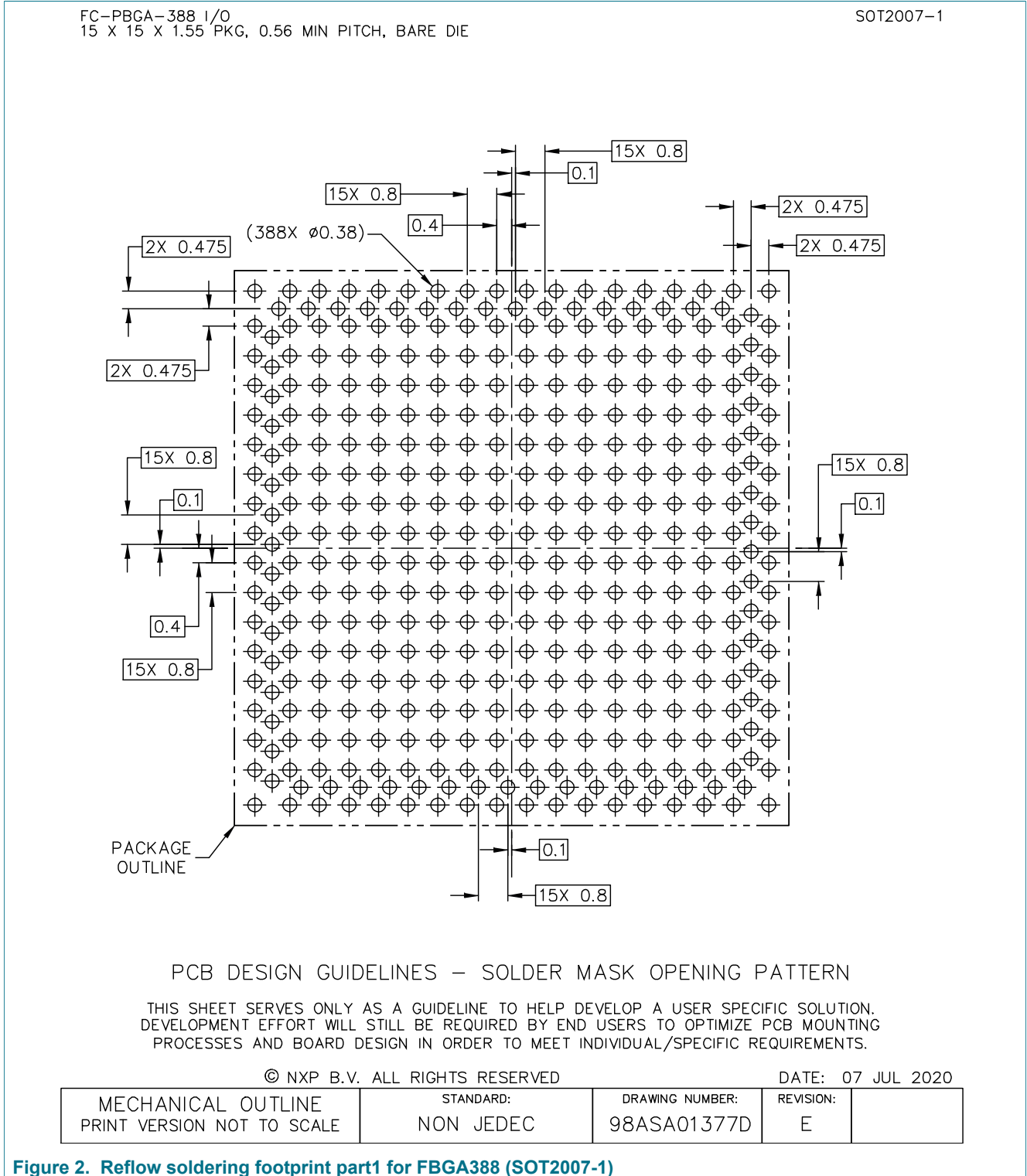


Figure 2. Reflow soldering footprint part1 for FBGA388 (SOT2007-1)

LPGA388, low profile ball grid array package, 388 terminals, 0.56 mm minimum pitch, 15 mm x 15 mm x 1.55 mm body, bare die

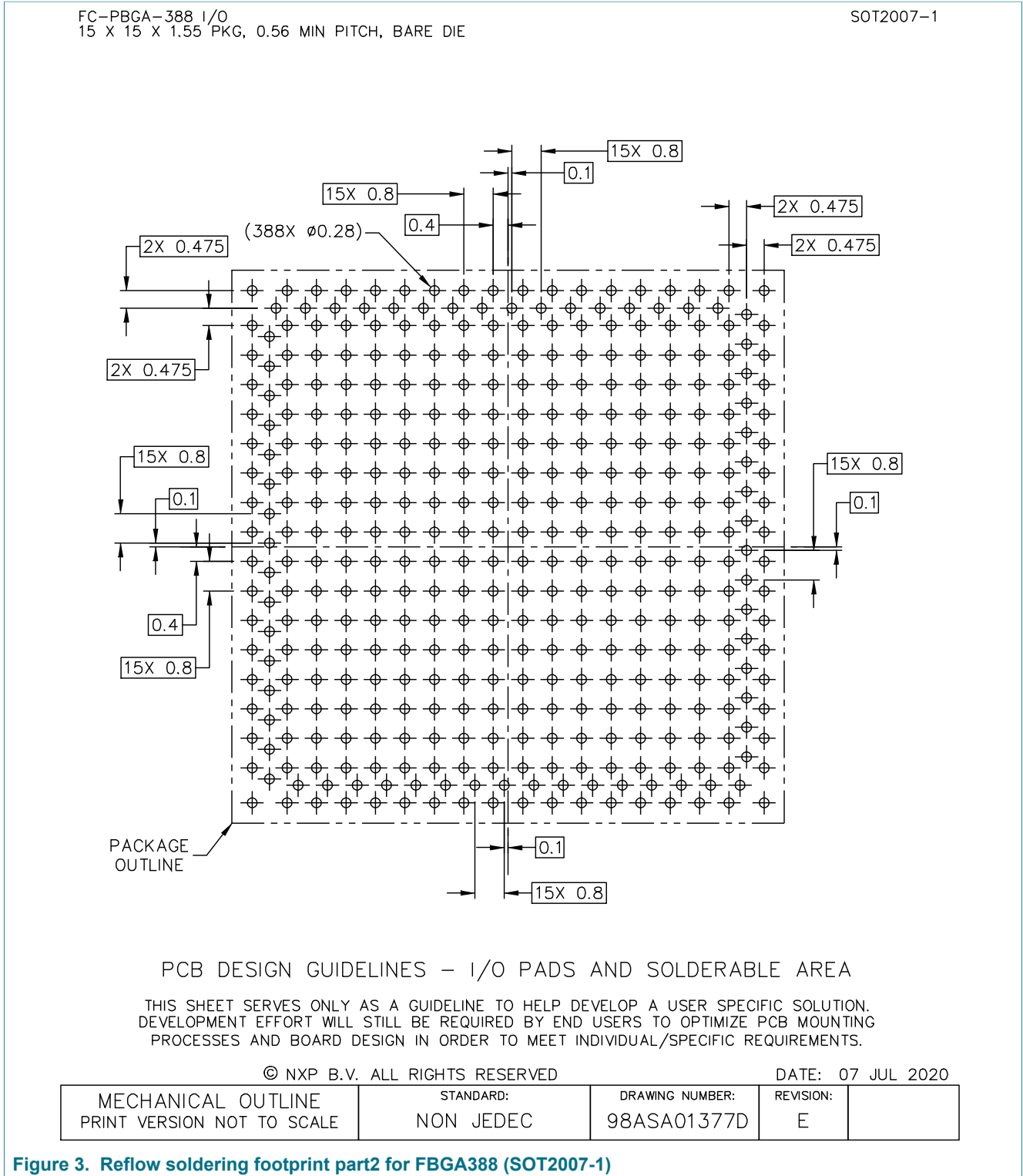
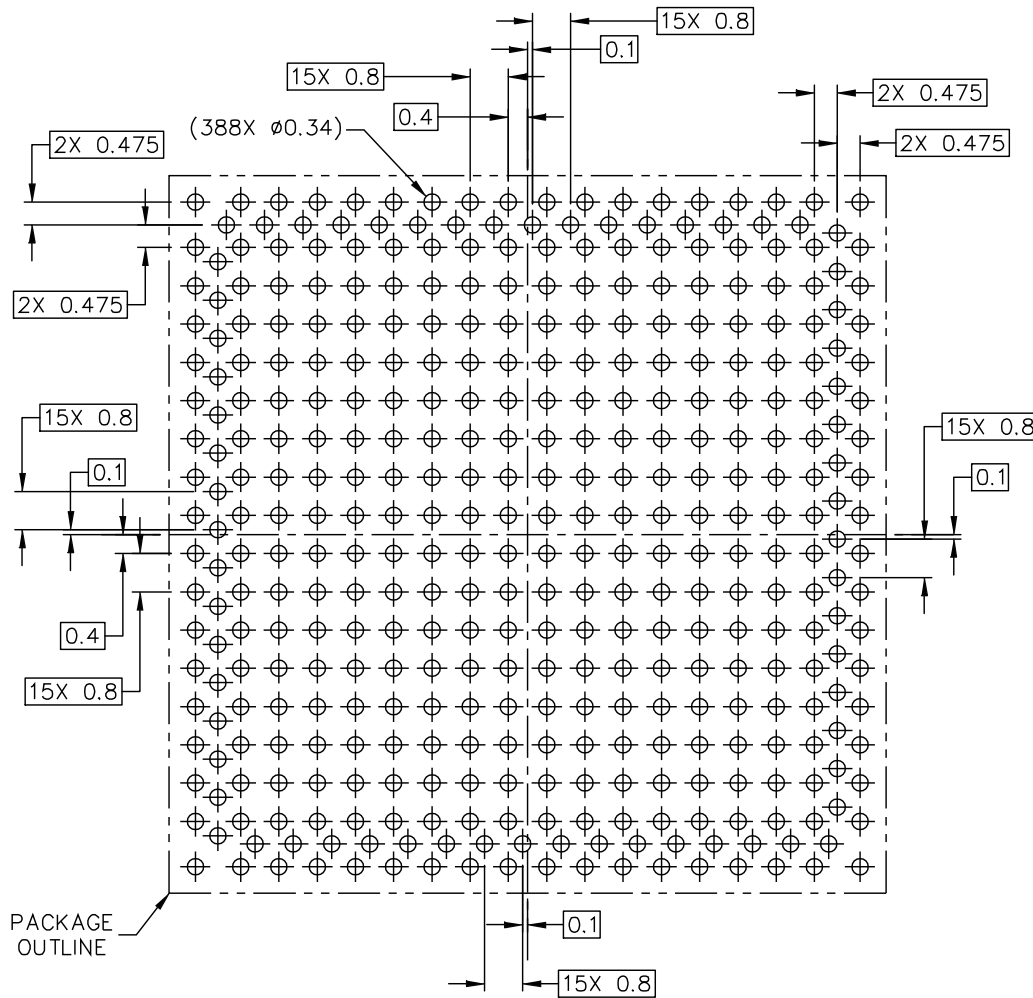


Figure 3. Reflow soldering footprint part2 for FBGA388 (SOT2007-1)

LPGA388, low profile ball grid array package, 388 terminals, 0.56 mm minimum pitch, 15 mm x 15 mm x 1.55 mm body, bare die

FC-PBGA-388 I/O  
15 X 15 X 1.55 PKG, 0.56 MIN PITCH, BARE DIE

SOT2007-1



RECOMMENDED STENCIL THICKNESS 0.125MM

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

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DATE: 07 JUL 2020

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01377D	REVISION: E
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Figure 4. Reflow soldering footprint part3 for FBGA388 (SOT2007-1)

**LBGA388, low profile ball grid array package, 388 terminals, 0.56 mm minimum pitch, 15 mm x 15 mm x 1.55 mm body, bare die**

FC-PBGA-388 I/O  
15 X 15 X 1.55 PKG, 0.56 MIN PITCH, BARE DIE

SOT2007-1

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3.  MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C. RAW BALL DIAMETER IS 0.325MM.
4.  DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5.  PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
6. ALL DIMENSIONS ARE SYMMETRIC ACROSS THE PACKAGE CENTER LINES, UNLESS DIMENSIONED OTHERWISE.

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**Figure 5. Package outline note FBGA388 (SOT2007-1)**

## 4 Legal information

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